

Amendments to the Specification

Please add the following paragraph between the title and the first line of text as follows:

7/7/06 This is a Division of Application No. 10/011,291 filed December 11, 2001, which ^{now abandoned} claims the benefit of Japanese Patent Application No. 2000-384382 filed December 18, 2000.

The entire disclosure of the prior application is hereby incorporated by reference herein in its entirety.

Please replace the paragraph beginning on page 43, line 6, with the following rewritten paragraph:

FIG. 22 is a characteristic diagram illustrating another example of the results of measurements conducted to determine the relationship between the processing conditions for the adhering step and change in the characteristics of the electronic component 13 between before and after the adhering step. FIG. 22 shows changes in the transmission characteristics of the band pass filter between before and after the adhering step. In FIG. 22, the horizontal axis represents frequency and the vertical axis represents S_{21} parameter. FIG. 22 shows in detail the transmission characteristics in the frequency range where the S_{21} parameter has values from 0.0 to -5.0 dB. In this example, the adhering step was carried out under four different conditions, that is, by varying the number of times of the heat treatment, to measure the transmission characteristics of the band pass filter after the adhering step each time. At each heat treatment, the resin film 15 was heated at 180°C for one hour. In this example, the resin film 15 is formed of an epoxy-based resin, and the content of a hardening accelerator in the epoxy-based resin is 0.1 wt%. In FIG. 22, the solid line indicates the transmission characteristics obtained before the electronic component 13 is sealed, that is, before the adhering step. On the other hand, the alternate long and short dashed lines indicate the